

MD50D65JB3H

650V 50A Trench and Field Stop IGBT

DESCRIPTION :

- High ruggedness performance
- Easy parallel switching capability
- High efficiency for inverters.
- RoHS compliant.

TYPICAL APPLICATIONS:

- PFC appliances
- Uninterruptible power supplies
- Solar inverter



TO-247

IGBT

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

		Quarteral	Mahaa	1.1.4.14
Characteristic	Condition	Symbol	Value	Unit
Collector-Emitter Voltage		V _{CES}	650	V
Continuous collector current	Tc=25℃ Tc=100℃	I _{C nom}	100 50	А
Pulsed collector current	t_P limited by Tvjmax	I _{CM}	200	А
Gate emitter voltage		V_{GE}	±20	V
Power dissipation	Tc=25℃ Tc=100℃	P _{tot}	535 267	W
Temperature under switching conditions		Tvj op	-40~+175	°C
Storage temperature		T _{STG}	-55~+150	°C

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Max.	Unit
IGBT thermal resistance, junction - case		R _{th(j-C)}	0.28	K/W
Diode thermal resistance, junction - case		R _{th(j-C)}	0.42	K/W
Thermal resistance, junction - ambient		$R_{th(j-A)}$	40	K/W

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Collector-emitter cut-off current VCE=650V, VGE=0V Tvj=25℃	I _{CES}			50	uA
Gate-emitter leakage current VCE=0V, VGE=20V Tvj=25℃	I _{GES}			100	nA
Gate-Emitter threshold voltage IC=1.0mA, VGE= VCE Tvj=25 $^\circ$ C	$V_{GE(th)}$	5.0	5.4	5.6	V
Collector-Emitter saturation voltage VGE=15V, IC=50A Tvj=25℃ VGE=15V, IC=50A Tvj=175℃	$V_{CE(SAT)}$		1.8 2.3		V
Input capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{ies}		4820		pF
Output capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{oes}		170		pF
Reverse transfer capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{res}		37		pF
Gate charge IC = 50A, VGE = 15 V,VCC =520V Tvj=25℃	Q _G		158		nC
Turn-on delay time IC=50A, VCC=400 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	td _(ON)		52 49		ns
Rise time IC=50A, VCC=400 V Tvj=25℃ VGE=0/15 V, RG=10 Ω Tvj=175℃ (inductive load)	tr		82 85		ns
Turn-off delay time IC=50A, VCC=400 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	td _(OFF)		193 210		ns
Fall time IC=50A, VCC=400 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	tf		61 68		ns
Turn-on energy IC=50A, VCC=400 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	E _(ON)		1.7 2.5		mJ

Turn-off energy loss per pulse IC=50A, VCC=400 V Tvj=25 $^{\circ}$ C VGE=0/15 V, RG=10 Ω Tvj=175 $^{\circ}$ C (inductive load)	E _(OFF)	1.0 1.0		mJ
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Diode

MAXIMUM RATINGS (Tvj=25 $^\circ\!\!{\rm C}$ unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Repetitive peak reverse voltage	Tvj=25 ℃	V _{RRM}	650	V
Continuous forward current	Tc=100℃	I _F	50	А
Diode maximum current	t_P limited by Tvj max	I _{FM}	200	A

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Forward voltage IF=50A, VGE=0 V Tvj=25℃ IF=50A, VGE=0 V Tvj=175℃	V _F		1.8 1.4		V
Reverse Recovered Time IF=50 A, Tvj=25℃ -diF/dt =800A/µs Tvj=175℃ VR=400 V	T _{rr}		82 132		ns
Peak reverse recovery current IF=50 A, Tvj=25℃ -diF/dt =800A/µs Tvj=175℃ VR=400 V	I _{RRM}		15 26		A
Reverse Recovered charge IF=50 A, Tvj=25℃ -diF/dt =800A/µs Tvj=175℃ VR=400 V	Q _{rr}		698 2194		nC

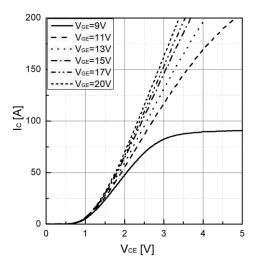


Figure 1. Typical output characteristics (Tvj=25 $^{\circ}$ C)

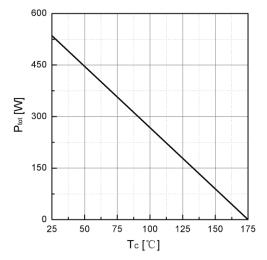


Figure 3. Power dissipation as a function of TC

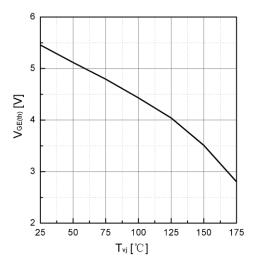


Figure 5. Typical VGE(th) as a function of Tvj ($I_C=1mA$)

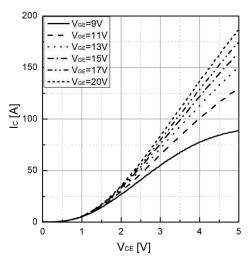


Figure 2. Typical output characteristics (Tvj=175°C)

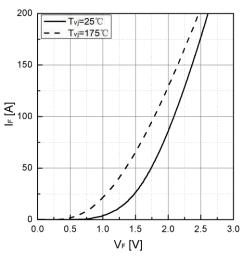


Figure 4. Typical IF as a function of VF

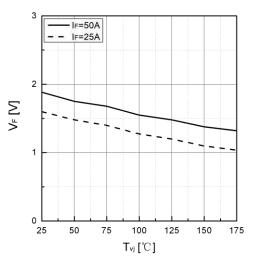


Figure 6. Typical VF as a function of Tvj

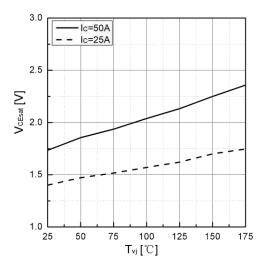


Figure 7. Typical VCEsat as a function of Tvj

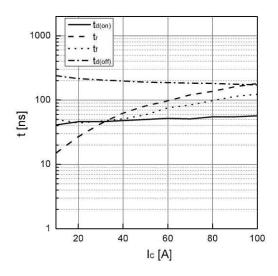


Figure 9. Typical switching times as a function of IC

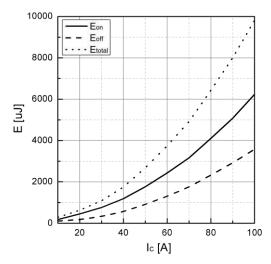


Figure 11. Typical switching energy losses as a function of IC

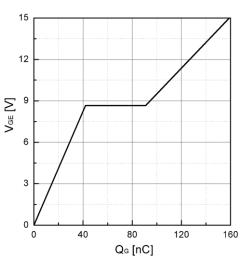


Figure 8. Typical Gate charge

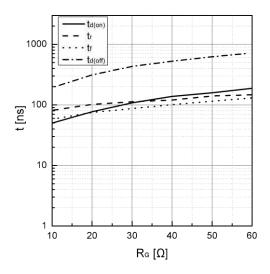


Figure 10. Typical switching times as a function of RG

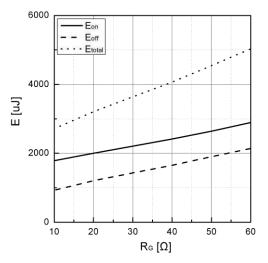
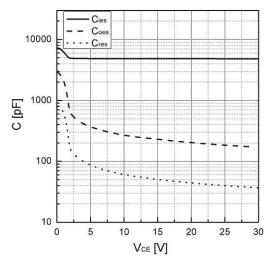
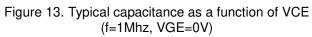


Figure 12. Typical switching energy losses as a function of RG





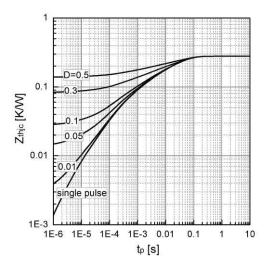
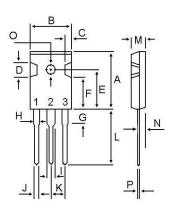


Figure 14. Transient thermal impedance, IGBT

Circuit diagram

• Package outlines : Dimensions in (mm)



	MILLIMETERS			
DIM				
Unit	MIN	MAX		
A	20.80	21.80		
В	15.38	16.20		
С	1.90	2.70		
D	5.10	6.10		
E	14.50	15.50		
F	11.20	13.20		
G	3.75	4.35		
Н	1.90	2.30		
1	2.90	3.30		
J	1.00	1.40		
к	5.26	5.66		
L	19.50	20.50		
М	4.68	5.36		
N	2.30	2.60		
0	3.45	3.85		
Р	0.48	0.72		



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